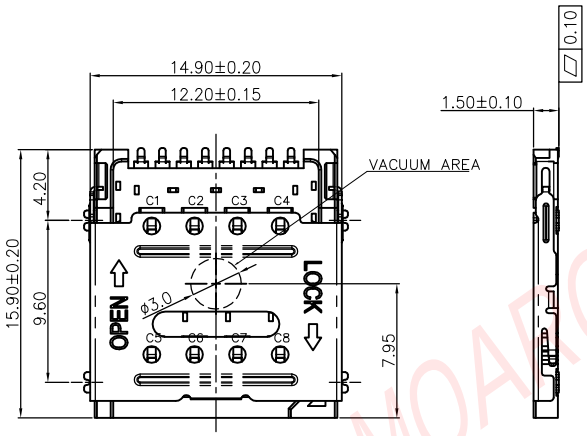
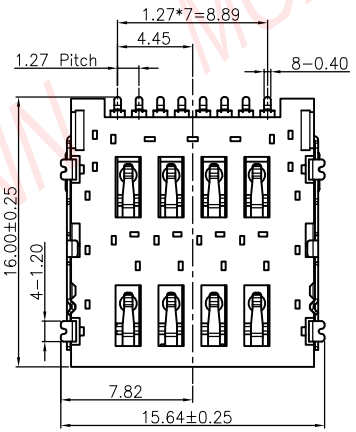
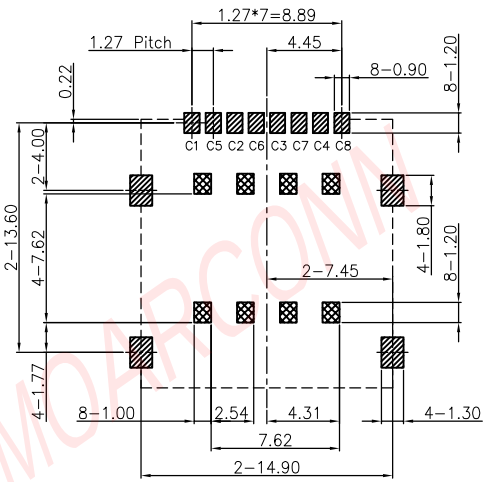
All materials, plating and process meet HF requirements.

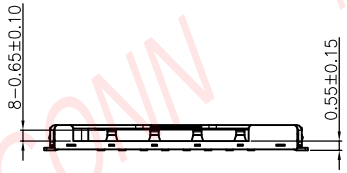


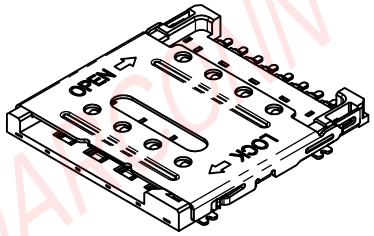




RECOMMENDED PCB LAYOUT (TOP VIEW)
GENERAL TOLERANCE ±0.05

PAD AREA
NO PATTERN AND VIA HOLE IN THIS AREA
CONN. OUTLINE





PIN NO.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

Specification

MATERIAL:

Insulator: High Temperature Thermoplastic, UL94-V0
Contact: Copper Alloy
Cover: Stainless Stell

PLATING:

Contact: Plated 50u" Ni Overall, Contact Au 1u", Solder Tile GoldFlash

Electrical:

Current Rating :0.5mA AC/DC max.
Voltage Rating :5V AC/DC
Ambient Temperature Range :-25° C~+85° C
Storage Temperature Range :-40° C~+85° C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000MΩ min./500V DC
Mating Cycles:5,000 Insertions
Reflow peak temp.: 260° C ±5° C, 3~5 S

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
X0	----	NEW RELEASE	Alexander	2026.04.27

MOARCONN®
More Connections Smart Future

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2°

DONG GUAN MOARCONN ELECTRONIC Co., Ltd.

PRODUCT NAME : MicroSIM H1.5 Hinge Type	DRAWING: Alexander	DATE: 2026.04.27
PRODUCT NO. : MS150-T1120-02	CHECK:	DATE:
DRAWING NO. : D-MS150-T1120-02	APPROVED:	DATE:
	SCALE: 1:1 / DWG ID: C D / REV.: X0	PAGE: 1 OF 1

MOARCONN